# MMBD6050LT1

# **Switching Diode**

#### **Features**

• Pb-Free Packages are Available

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Reverse Voltage	V <sub>R</sub>	70	Vdc
Forward Current	I <sub>F</sub>	200	mAdc
Peak Forward Surge Current	I <sub>FM(surge)</sub>	500	mAdc

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR–5 Board, (Note 1) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	300 2.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

- 1.  $FR-5 = 1.0 \times 0.75 \times 0.062$  in.
- 2. Alumina = 0.4 x 0.3 x 0.024 in. 99.5% alumina.

# **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Rating	Symbol	Min	Max	Unit	
OFF CHARACTERISTICS					
Reverse Breakdown Voltage (I <sub>(BR)</sub> = 100 μAdc)	V <sub>R</sub>	70	-	Vdc	
Reverse Voltage Leakage Current (V <sub>R</sub> = 50 Vdc)	lF	-	0.1	μAdc	
Forward Voltage (I <sub>F</sub> = 1.0 mAdc) (I <sub>F</sub> = 100 mAdc)	I <sub>FM(surge)</sub>	0.55 0.85	0.7 1.1	Vdc	
Reverse Recovery Time (Figure 1) (I <sub>F</sub> = I <sub>R</sub> = 10 mAdc, I <sub>R(REC)</sub> = 1.0 mAdc)	lF	-	4.0	ns	
Capacitance (V <sub>R</sub> = 0 V)	I <sub>FM(surge)</sub>	-	2.5	pF	



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SOT-23 (TO-236) CASE 318 STYLE 8

#### **MARKING DIAGRAM**



5A = Device Code

M = Date Code\*

= Pb–Free Package

(Note: Microdot may be in either location)

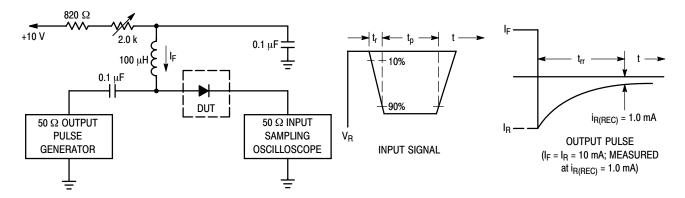
\*Date Code orientation and/or overbar may vary depending upon manufacturing location.

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MMBD6050LT1	SOT-23	3,000 / Tape & Reel
MMBD6050LT1G	SOT-23 (Pb-Free)	3,000 / Tape & Reel
MMBD6050LT3	SOT-23	10,000/Tape & Reel
MMBD6050LT3G	SOT-23 (Pb-Free)	10,000/Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# **MMBD6050LT1**



Notes: 1. A 2.0 k $\Omega$  variable resistor adjusted for a Forward Current (I<sub>F</sub>) of 10 mA.

- 2. Input pulse is adjusted so  $I_{R(peak)}$  is equal to 10 mA.
- 3. t<sub>p</sub> » t<sub>rr</sub>

Figure 1. Recovery Time Equivalent Test Circuit

# **TYPICAL CHARACTERISTICS**

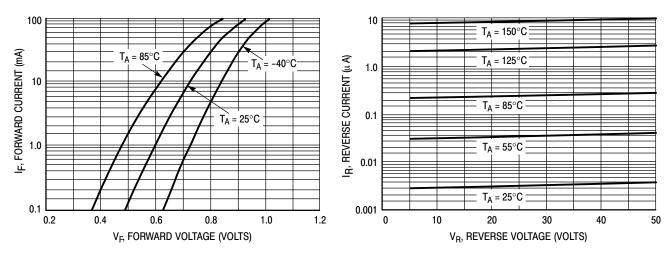


Figure 2. Forward Voltage

Figure 3. Leakage Current

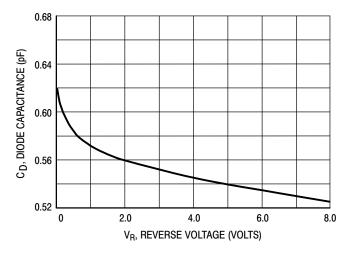
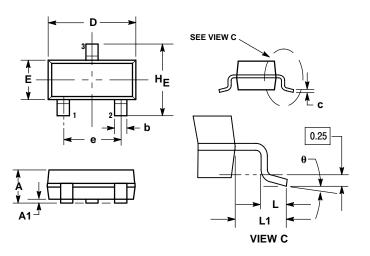


Figure 4. Capacitance

### MMBD6050LT1

#### PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AN** 



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER

  - ANSI Y14.5M, 1982.

    2. CONTROLLING DIMENSION: INCH.

    3. MAXIMUM LEAD THICKNESS INCLUDES
    LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
  - 4. 318-01 THRU -07 AND -09 OBSOLETE, NEW STANDARD 318-08.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
С	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2 10	2 40	2 64	0.083	0.094	0.104

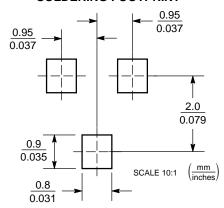
#### STYLE 8:

PIN 1. ANODE

NO CONNECTION

CATHODE

# **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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